The Institute for Interconnecting and Packaging Electronic Circuits

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Design Standard for Thick Film Multilayer Hybrid Circuits

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Standardization

In May 1995 the IPC's Technical Activities Executive Committee adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:
• Show relationship to DFM & DFE
• Minimize time to market
• Contain simple (simplified) language
• Just include spec information
• Focus on end product performance
• Include a feed back system on use and problems for future improvement

Standards Should Not:
• Inhibit innovation
• Increase time-to-market
• Keep people out
• Increase cycle time
• Tell you how to make something
• Contain anything that cannot be defended with data

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The material in this standard was developed by the Hybrid Design Task Group of the Hybrid & Related Technologies Committee of the Institute for Interconnecting and Packaging Electronic Circuits.

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